

TFT-LCD PRODUCT SPECIFICATION

PART NUMBER:	USMP-TT020TR-01B
DESCRIPTION:	2.0" TFT LCD with 176 x 220 resolution,
	8-bit interface for 80 system interface, and LED backlight.

ISSUE DATE	APPROVED BY (Customer Use Only)	CHECKED BY	PREPARED BY
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History of Version

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Date	Ver.	Edi.	Description	Page	Design by
11/19/2008	01	001	New Drawing	-	Binbin
12/24/2008	01	002	New sample	-	Binbin



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1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	176(R · G · B) *220 Dots
LCD Type	Active matrix TFT, Transmissive type
Screen size(inch)	2.0 inch
Viewing Direction	12 O'clock
Color configuration	R. G. B. vertical stripe
Backlight	LED B/L
Interface	8-bit interface for 80 system
Driver IC	HX8340-B (Support 65K,262K Colors)
Viewing Direction Color configuration Backlight Interface	12 O'clock R. G. B. vertical stripe LED B/L 8-bit interface for 80 system

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	38.4 (W) * 51.4(L) * 2.4max (H)	mm

TFT LCD panel

Item	Standard Value	Unit
Viewing Area	32.68(W) * 40.6 (L)	mm
Active Area	31.68(W) * 39.6 (L)	mm

Note: For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
	VDD	ı	-0.3	3.6	
System Dower Supply Voltage	VGH	VDD=2.8V	10	15.3	V
System Power Supply Voltage	VGL	VDD=2.8V	-13.5	-7.5	
	VGH- VGL	VDD=2.8V	17.5	28.8	
Input Voltage	VIN	-	-0.3	VDD+0.5	V
Operating Temperature	TOP	-	-20	70	°C
Storage Temperature	TST	-	-30	80	°C
Storage Humidity	HD	Ta < 60 °C	-	90	%RH

1.4 DC Electrical Characteristics

Module GND = 0V, Ta = 25°C

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VDD	-	2.6	2.8	3.0	V
Input High Voltage	V _{IH}	-	0.7*VDD	-	VDD	V
Input Low Voltage	V _{IL}	-	GND	-	0.3*VDD	V
Output High Voltage	V _{OH}	IOH = -1.0 mA	0.8*VDD	-	VDD	V
Output Low Voltage	V_{OL}	IOL = +1.0 mA	GND	-	0.2*VDD	V
Supply Current	IDD	VDD = 2.8 V Pattern= black *1	-	4	6	mA

5

Note *1: Maximum current display



1.5 Optical Characteristics

TFT LCD Panel

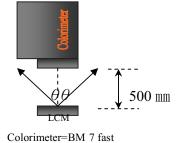
VDD =2.8V, Ta=25°C

Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response tim	ne	Tr + Tf	Ta = 25°C θX, θY = 0°	-	34	51	ms	Note2
	Тор	θΥ+		-	50	-		
Viewing angle	Bottom	θΥ-	CR ≥ 10	-	25	-	Deg.	Note4
viewing angle	Left	θX-	UK ≥ 10	-	40	-	Deg.	NOIE4
	Right	θX+		-	40	-		
Contrast rati	0	CR		150	200	-	-	Note3
	White	Х		0.22	0.27	0.32		
	VVIIILE	Υ	Ta = 25°C	0.27	0.32	0.37	_	
0 10	D - 1	Х		0.59	0.64	0.69		
Color of CIE Coordinate	Red	Red Y		0.29	0.34	0.39		Note1
(With B/L and TP)	Green	Х	θX , $\theta Y = 0^{\circ}$	0.27	0.32	0.37		Note
(With B/E and Tr)	Green	Υ		0.57	0.62	0.67		
	Blue	Х		0.09	0.14	0.19		
	Diue	Υ		0.04	0.09	0.14		
Average Brightr	ness							
Pattern= white		IV	IF= 60mA	140	160	-	cd/m ²	Note1
(With B/L)								
Uniformity (With B/L)		△В	IF= 60mA	80	-	-	%	Note1

Note1:

- $1 : \triangle B=B(min) / B(max) \times 100\%$
- 2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25° ± 5° / 60 ±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta = 0^{\circ})$
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





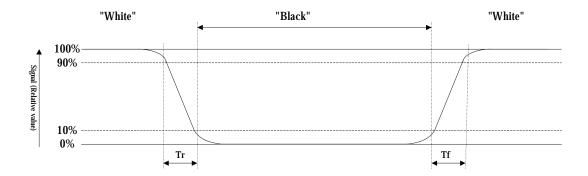
(800) 741-7755



Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

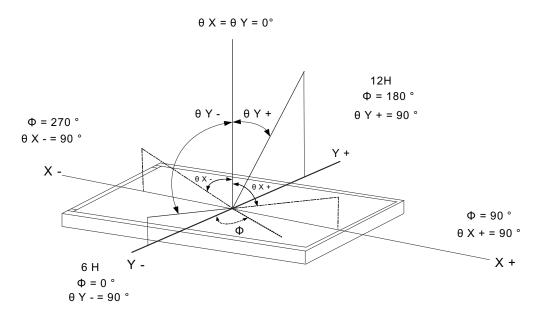
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





1.6 Backlight & LED Characteristics

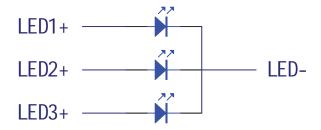
LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Voltage	VF	Ta =25°ℂ	-	4	V
Forward Current	IF	Ta =25°ℂ	-	90	mA
Reverse Voltage	VR	Ta =25°ℂ	-	5	V
Reverse Current	IR	Ta =25°ℂ	-	0.15	mA
Power Dissipation	PD	Ta =25°ℂ	-	360	mW

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF		-	3.3	-	V
Average Brightness (without LCD)	IV	IF= 60mA	2800	3200	-	cd/m ²
Color of CIE Coordinate	Х		-	0.28	-	
(without LCD)	Υ		-	0.28	-	-
Color			White	•	•	•





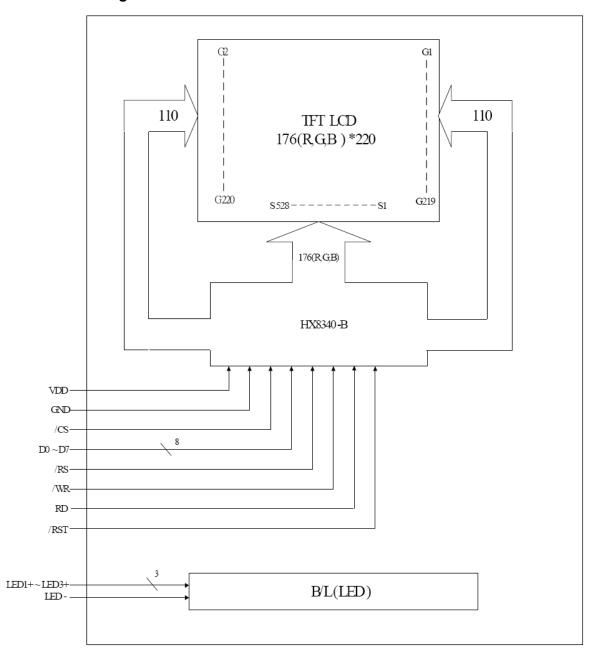
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

Pin NO	Symbol	Function
1	GND	Signal ground.
2	X+	NC.
3	Y+	NC.
4	X-	NC.
5	Y-	NC.
6	GND	Signal ground.
7	VDD	Power supply 2.8V.
8	/CS	Chip select signal. Low: chip can be accessed. High: chip cannot be accessed.
9	/RS	The signal for register index or register command select. Low: Register index or internal status (in read operation); High: Register command.
10	WR	Serves as a write signal and writes data at the rising edge in i80 system interface.
11	RD	Low: Write; High: Read Serves as a read signal and reads data at the low level in i80 system interface
12	D0	Data bus bit 0
13	D1	Data bus bit 1
14	D2	Data bus bit 2
15	D3	Data bus bit 3
16	D4	Data bus bit 4
17	D5	Data bus bit 5
18	D6	Data bus bit 6
19	D7	Data bus bit 7
20	/RST	Reset pin. Setting either pin low initializes the LSI. Must be reset after power is supplied.
21	GND	Signal ground

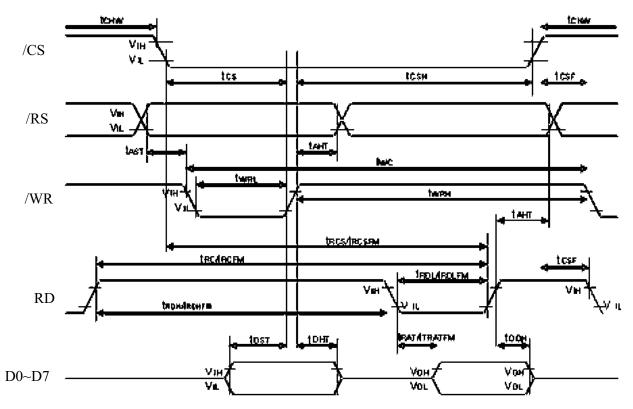


Pin NO	Symbol	Function
22	LED1+	Backlight LED1 anode input pin.
23	LED2+	Backlight LED2 anode input pin.
24	LED3+	Backlight LED3 anode input pin.
25	LED-	Backlight LED cathode input pin.



2.3 Timing Characteristics

i80-System Interface Timing Characteristics

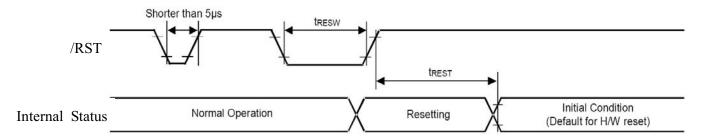


VDD=2.8V, Ta=25°C

Signal	Symbol	Parameter	Min.	Max.	Unit	Description
/D.C	t ast	Address setup time	0	-		
/RS	t aht	Address hold time (Write/Read)	10	-	ns	-
	t chw	Chip select "H" pulse width	0	-		
	t cs	Chip select setup time (Write)	15	-		
/00	trcs	Chip select setup time (Read ID)	45	-	ns	
/CS	t RCSFM	Chip select setup time (Read FM)	355	-	115	_
	tcsf	Chip select wait time (Write/Read)	10	-		
	t csH	Chip select hold time	10	-		
	twc	Write cycle	66	-		
/WR	twrh	Control pulse "H" duration	15	-	ns	-
	twrL	Control pulse "L" duration	15	-		
DD(ID)	t RC	Read cycle (ID)	160	-		
RD(ID)	t RDH	Control pulse "H" duration (ID)	90	-	ns	When read ID data
	t RDL	Control pulse "L" duration (ID)	45	-		
(6)	tпсгм	Read cycle (FM)	450	-		When read from frame
RD(FM)	t RDHFM	Control pulse "H" duration (FM)	90	-	ns	
	t RDLFM	Control pulse "L" duration (FM)	355	-		memory
	t DST	Data setup time	10	-		
D0 D5	t DHT	Data hold time	10	-		For maximum C. =30nE
D0~D7	t rat	Read access time (ID)	-	40	ns	For maximum C _L =30pF For minimum C _L =8pF
	t ratem	Read access time (FM)	-	340		For minimum CL-ope
	t odh	Output disable time	20	80		



Reset Timing Characteristics



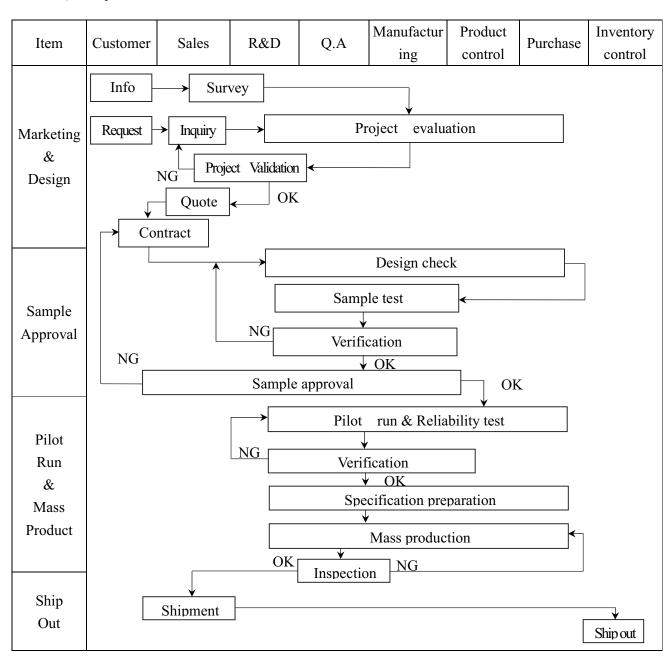
VDD=2.8V, Ta=25 $^{\circ}$ C

Symbol	Parameter	Related Pins	Min.	Тур.	Max.	Note	Units
t_{RESW}	Reset low pulse width	/RST	10	-	ı	•	μs
4	Paget complete time	-	-	-		When reset applied during Sleep In mode	ms
t _{REST}	Reset complete time	-	1	-	120	When reset applied during Sleep Out mode	ms

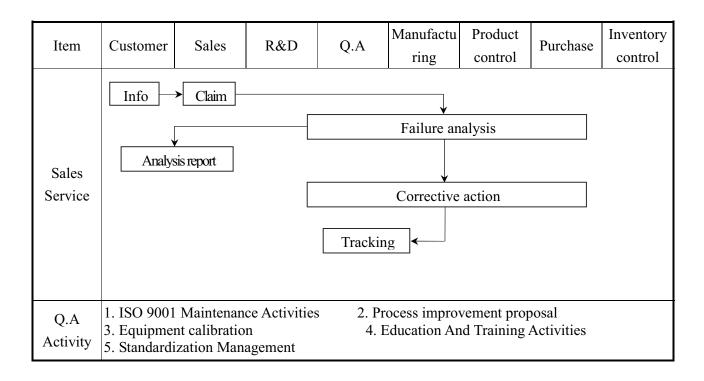


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2.Inspection Specification

♦Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level II.

♦Equipment : Gauge • MIL-STD • Sample

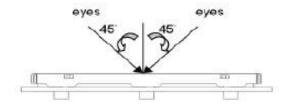
Defect Level: Major Defect AQL: 0.65 ; Minor Defect AQL: 1.5

♦OUT Going Defect Level: Sampling.

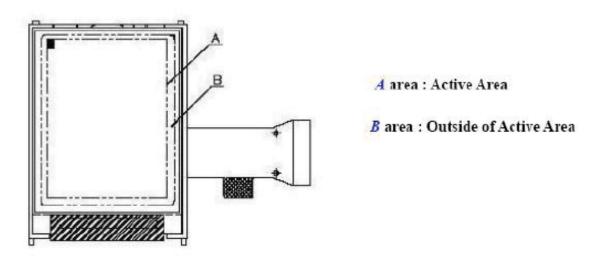
♦Standard of the product appearance test:

a. Manner of appearance test:

- (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
- (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



(4). Standard of inspection: (Unit: mm)



NO	Item		Criterion		Level	
		1. 1The part number production.	is inconsistent wi	th work order of	Major	
01	Product condition	1. 2 Mixed product ty	ypes.		Major	
		1. 3 Assembled in inv	erse direction.		Major	
02	Quantity	The quantity is incor	sistent with work	order of production.	Major	
03	Outline dimension	Product dimension a diagram.	nd structure mus	conform to structure	Major	
		4. 1 Missing line char	racter and icon.		Major	
		4. 2 No function or no display.				
04	Electrical Testing	4. 3 Display malfunction.				
*******		4. 4 LCD viewing angle defect.				
		4. 5 Current consum	ption exceeds pro	duct specifications.	Major	
		I	tem	Acceptance (Q'ty)		
		Dot Defect	Bright Dot	≦ 3		
		(Sub Pixel)	Joint Dot	≦ 2		
	Dot defect	Pixel Defect	Bright Dot	≤ 1		
05	(Bright dot \ Dark dot) On -display	5. 1 Inspection patter 5. 2 It is defined as d 5. 3 The distance bet R G B Sub Pixel (alone R orG orB)	blue screens. ot defect if defect ween two dot defe R G Pixe	ct ≧5 mm. B	Minor	



NO	Item		Criteri	on		Level	
		6. 1 Clear Spot	ts: mension	Acceptance	(Q'ty)		
		(diar	neter : Φ)	A area	B area		
			Φ ≤ 0.15	Ignore			
		0.15 <	$\Phi \leq 0.20$	3			
		0.20 <	$\Phi \leq 0.30$	3	Ignore		
	Round type		Φ > 0.30	0			
06		6. 2 Dim Spots	:	•		Minor	
00	→ _X ← ↓	Dir	mension	Acceptance	(Q'ty)	Willion	
	Y	(diar	neter : Φ)	A area	B area		
	<u> </u>		Φ ≤ 0.2	Ignore			
	Φ −(-1-2)/2	0.2 <	Φ ≤ 0.4	3	lamara		
	$\Phi = (x+y)/2$	0.4 <	$\Phi \leq 0.6$	1	Ignore		
			$\Phi > 0.6$	0			
		WI 6241					
		7. 1 Line:	nat can be removed	l.			
		Dimension		Acceptan	Acceptance (Q'ty)		
		Length (L)	Width (W)	A area	B area		
			$W \leq 0.0$	3 Ignore			
		L ≦5	$0.03 < W \le 0.0$	5 4			
	Line type	L ≦5	$0.05 < W \le 0.1$	3	Ignore		
	Line type		W > 0.1	As round			
	1		VV > 0.1	type			
07	✓ [‡] w	7. 2 Scratch:				Minor	
	→ L +	D	imension		ce (Q'ty)		
	L L	Length (L)	Width (W)	A area	B area		
	$\Phi = (x+y)/2$		W ≤ 0.0		_		
		L ≦5	0.03 <w< b=""> ≤ 0.0</w<>		_ .		
		L ≦5	$0.05 < W \le 0.1$		Ignore		
			W > 0.1	As round	'		
		L		type			
		%Ignore 7.1 tl	hat can be removed	,			



NO	Item	Criterion	Level
08	Bubble / Dent	$\begin{array}{ c c c c c }\hline \textbf{Dimension} & \textbf{Acceptance} & (Q'ty) \\ \hline (diameter: \Phi) & \textbf{A area} & \textbf{B area} \\ \hline & \Phi \leq 0.2 & \textbf{Ignore} \\ \hline & 0.2 < \Phi \leq 0.4 & 3 \\ \hline & 0.4 < \Phi \leq 0.5 & 1 \\ \hline & \Phi > 0.5 & 0 \\ \hline \end{array}$	Minor
	-	9. 1 Backlight can't work normally.	Major
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong. 9. 3 Illumination source flickers when lit.	Major Major
10	Newton's ring	N: Area of Newton's ring VA: LCM View Area N≦1/2*VA	Minor
		11. 1 Pin type \quantity \quantity \dimension must match type in structure diagram.	Major
		$11.2~\mathrm{No}$ short circuits in components on PCB or FPC .	Major
11	General appearance	11.3 Parts on PCB or FPC must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	Major
		11. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		11.5 The folding and peeled off in polarizer are not acceptable.	Minor
		$11.~6$ The PCB or FPC between B/L assembled distance(PCB or FPC) is $~\leq 1.~5~$ mm.	Minor

4. RELIABILITY TEST

4.1 Reliability Test Condition

High Temperature Storage Test Low Temperature Storage Test High Temperature / High Humidity Storage Test Temperature Cycling Storage Test	Keep in -30 $\pm 2^{\circ}$ C 96 hrs ,Hum Surrounding temperature, then Keep in +60°C / 90% R.H durat Surrounding temperature, then (Excluding the polarizer) -20° C \rightarrow +25°C \rightarrow (30mins) (5mins)	storage at normal condition 4hrs. idity: Except, storage at normal condition 4hrs. ion for 96 hrs storage at normal condition 4hrs. $+70^{\circ}\text{C} \rightarrow +25^{\circ}\text{C}$	Note1
Storage Test High Temperature / High Humidity Storage Test Temperature Cycling	Surrounding temperature, then Keep in +60°C / 90% R.H durat Surrounding temperature, then (Excluding the polarizer) -20°C -> +25°C -> (30mins) (5mins) 10 C Surrounding temperature, then Air Discharge:	storage at normal condition 4hrs. ion for 96 hrs storage at normal condition 4hrs. +70°C \rightarrow +25°C (30mins) (5mins) cycle storage at normal condition 4hrs. Contact Discharge:	Note1
High Humidity Storage Test Temperature Cycling	Surrounding temperature, then (Excluding the polarizer) $-20^{\circ} \longrightarrow +25^{\circ} \longrightarrow (30 \text{mins}) (5 \text{mins})$ $10^{\circ} \bigcirc$ Surrounding temperature, then Air Discharge:	+70°C → +25°C (30mins) (5mins) Sycle storage at normal condition 4hrs. Contact Discharge:	Note1
Cycling	(30mins) (5mins) 10 C Surrounding temperature, then Air Discharge:	(30mins) (5mins) Sycle storage at normal condition 4hrs. Contact Discharge:	
	S .	g .	
ESD Test	1. Temperature ambiance: 15°C 2. Humidity relative: 30% ~60° 3. Energy Storage Capacitance 4. Discharge Resistance(Rd): 33 5. Discharge, mode of operation Single Discharge (time between stance) (Tolerance if the output voltage)	discharge for each polarity +/- ~35℃ % (Cs+Cd):150pF±10% 0Ω±10% a: successive discharges at least 1 s)	Note2
Vibration Test (Packaged)	2. The amplitude of vibration :1	. 5 mm	
D T. 1	W≦ 9 Kg 9 Kg < W ≤18 Kg	100 80 60	Note3
		Vibration Test (Packaged) 2. The amplitude of vibration :1 3. Each direction (X \cdot Y \cdot Z) du Package Weight (W W≤ 9 Kg	(Packaged) 3. Each direction (X \times Y \times Z) duration for 2 Hrs Package Weight (W) Drop Height (cm) W \leq 9 Kg 100 9 Kg < W \leq 18 Kg 80

%Note1: a.No LC air bubble & leakage.

b.No display function related objection contrast before test.



※Note2 : No error of operational function after rebooting.

%Note3: The inspection of appearance√ the whole structure no error.



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25°C ± 5°C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period
 - The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility
 - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

(2.59)

(3.09)

32.68(LCD V.A) 31.68(LCD A.A)

(2.86) (3.36)

2.4MAX 0.85

(0.7)

(3.2)

(2.2)

36.4±0.1

1.0

38.4±0.1 35.1(LCD)

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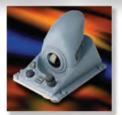
Peripheral Devices

Our full line of peripheral devices includes keyboards, trackballs, and printers. These rugged industrial products are designed to meet your demanding requirements and are available as both standard and custom solutions.

Keyboards



Trackballs Aerospace Trackballs



Joysticks



Printers

